

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Alcoe *et al.*

Art Unit:

Serial No.:

Dkt. No.: END920010111US2

Filed:

Examiner:

Title: MODULE WITH ADHESIVELY ATTACHED HEAT SINK

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No.

10/058,999; filed on 1/29/2002. *Pat. 6,744,132*

Please amend the paragraphs beginning on page 1, line 13 and ending on page 2, line 20
as follows:

The present invention provides an electronic structure, comprising:

a substrate;

a semiconductor device electrically coupled to the substrate;

a stiffener ring adhesively coupled to the substrate, wherein the stiffener ring surrounds
the semiconductor; and

a cover plate on a top surface of the semiconductor and on a top surface of the stiffener

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